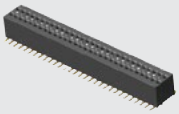
samtec

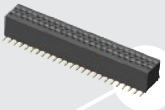


CLE–130–01–G–DV



CLE–108–01–G–DV

CLE–125–01–G–DV



**(0.80 mm) .0315"**

**CLE SERIES**

# COST-EFFECTIVE MICRO SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLE

**Insulator Material:**
Black Liquid Crystal Polymer
**Contact Material:**
BeCu
**Plating:**
Au over 50 µ" (1.27 µm) Ni
**Current Rating (CLE/FTE):**
2.7 A per pin
(2 pins powered)
**Operating Temp Range:**
-55 °C to +125 °C
**Insertion Depth:**
Top Entry = (1.73 mm) .068" to (3.18 mm) .125" with (0.38 mm) .015" wipe, or pass-through
Bottom Entry = (3.23 mm) .127" minimum plus board thickness
**Normal Force:**
75 grams (0.73 N)
**Max Cycles:**
100 with 10 µ" (0.25 µm) Au
**RoHS Compliant:**
Yes

## PROCESSING

**Lead-Free Solderable:**
Yes
**SMT Lead Coplanarity:**
(0.10 mm) .004" max (04-65)
(0.15 mm) .006" max (66-90)

## RECOGNITIONS

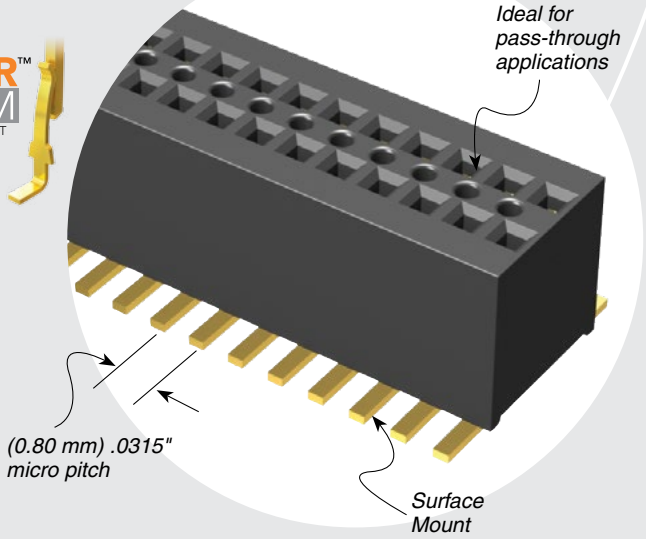
For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

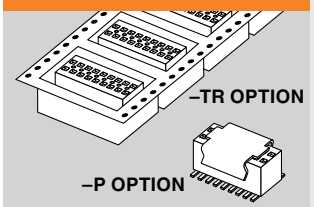
**Note:**
Some lengths, styles and options are non-standard, non-returnable.

**Mates with:**
FTE, AW

TIGER™ BEAM CONTACT




## OPTIONS



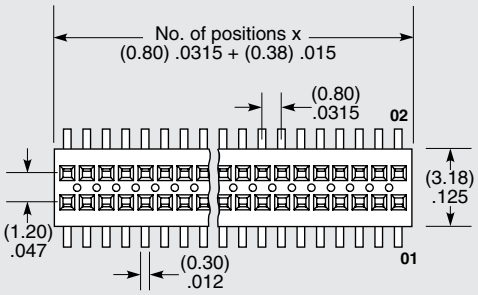

| CLE | – | 1 | NO. PINS PER ROW | – | 01 | – | PLATING OPTION | – | DV | – | OPTIONS |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | 04 thru 90 | | | | –G = 10 µ" (0.25 µm) Gold | | | | |

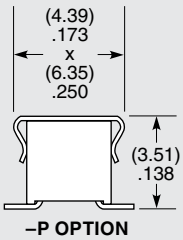
**–A**
= Alignment Pin (4 positions minimum) Metal or plastic at Samtec discretion.

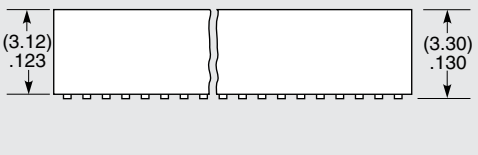
**–K**
= (3.50 mm) .138" DIA Polyimide film Pick & Place Pad (8 positions minimum)

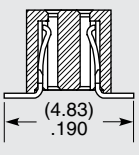
**–P**
= Metal Pick & Place Pad (8 positions minimum)

**–TR**
= Tape & Reel Packaging




Due to technical progress, all designs, specifications and components are subject to change without notice.



All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.